

Amendments to the claims:

Claims 1-21 (canceled)

Claim 22 (previously presented): A slurry for polishing a barrier layer that serves to isolate a copper layer from a dielectric layer comprising a mixture of:

about 14.7 grams per liter of a citric acid salt;

between about 4.4% and about 8.8% by volume of a silica based abrasive; and

about .38 grams per liter of a 30% H₂O₂ solution.

Claim 23 (previously presented): The slurry of claim 22 wherein the mixture includes about 8.8% by volume of a precipitated silica abrasive, has a pH that is about 7.4, and wherein the citric acid salt is potassium citrate.

Claims 24-26 (canceled)